

Product Information Sheet

MATERIAL ID:

EPO-TEK® OG159-2

Date: 08/2007

Per:

Rev: I

Material Description:

A single component, high viscosity, UV curable epoxy adhesive designed for sealing glass plates together in the LCD/OLED/display industry. It contains 1mil glass beads for bond line control. Common applications include semiconductor, electro-optics, fiber optic, and scientific/OEM. It can be applied by screen printing or dispensing techniques. It is capable of coating, adhering, sealing, and encapsulating devices.

Number of Components:

Single

Mix Ratio by weight:

N/A

Cure Schedule (minimum)*

100mW/cm² for 1 minute @ 320-500 nm (depending on thickness)

Specific Gravity:

1.18 --- Part A: Part B:

Pot Life:

N/A

Shelf Life:

One year at room temperature

NOTE: Container(s) should be kept closed in a dark location when not in use.

*Please see Applications Note(s) available on our website.

MATERIAL CHARACTERISTICS: *To be used as a guide only, not as a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results.*

* denotes test on lot acceptance basis; Cure condition: varies as required

PHYSICAL PROPERTIES:	
*Color (before cure):	White
*Consistency:	Thixotropic paste
*Viscosity (23°C):	
@ 2.5 rpm	100,000-140,000 cPs
Thixotropic Index:	N/A
*Glass Transition	≥ 30 °C (Post-Cure)
	Dynamic Scan 20—200°C; Ramp -10—200°C @ 20°C/Min)
Coefficient of Thermal Expansion (CTE):	
Below Tg:	58 x 10 ⁻⁶ in/in°C
Above Tg:	244 x 10 ⁻⁶ in/in°C
Shore D Hardness:	69
Die Shear @ 23°C:	≥ 5 Kg / 1,700 psi
Degradation Temp:	443 °C
Weight Loss:	
@ 200°C:	0.13 %
@ 250°C:	0.44 %
@ 300°C:	0.97 %
Operating Temp:	
Continuous:	- 55°C to + 200°C
Intermittent:	- 55°C to + 300°C
Storage Modulus @ 23°C:	341,084 psi
*Particle Size:	≤ 30 microns
OPTICAL PROPERTIES @ 23°C:	
Spectral Transmission:	>98 % @ 580-2000 nm
	>90 % @ 400 nm
Refractive Index (uncured):	1.5679 @ 589 nm